

Appl. No. : 09/389,720
Filed : September 3, 1999

CLEAN COPY OF PENDING CLAIMS

20. An assembly, comprising:
a film including a plurality of substrate units with each of said plurality of substrate units being adapted to electrically interface with a corresponding die, each one of said plurality of substrate units being generally defined on said film between a pair of flanking slots, and
a carrier in mechanical communication with said film for providing enhanced rigidity to said film by being sized and configured to add material at selected regions of said film.
21. The assembly of Claim 20, wherein said plurality of substrate units are grouped into substrate sets.
22. The assembly of Claim 21, wherein said substrate sets comprises three substrate units.
23. The assembly of Claim 22, wherein said carrier further comprises a plurality of cross bars and wherein each cross bar is located near a substrate set.
24. The assembly of Claim 20, wherein said plurality of dies comprise lead-over-chips (LOC).
26. The assembly of Claim 20, wherein said film comprises polyimide.
27. The assembly of Claim 20, wherein each one of said plurality of substrate units includes a substantially central cavity.
29. The assembly of Claim 20, wherein each one of said plurality of substrate units includes a pair of adhesive tabs.

Appl. No. : 09/389,720
Filed : September 3, 1999

30. The assembly of Claim 20, wherein each one of said plurality of substrate units includes a plurality of alignment holes.